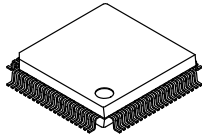
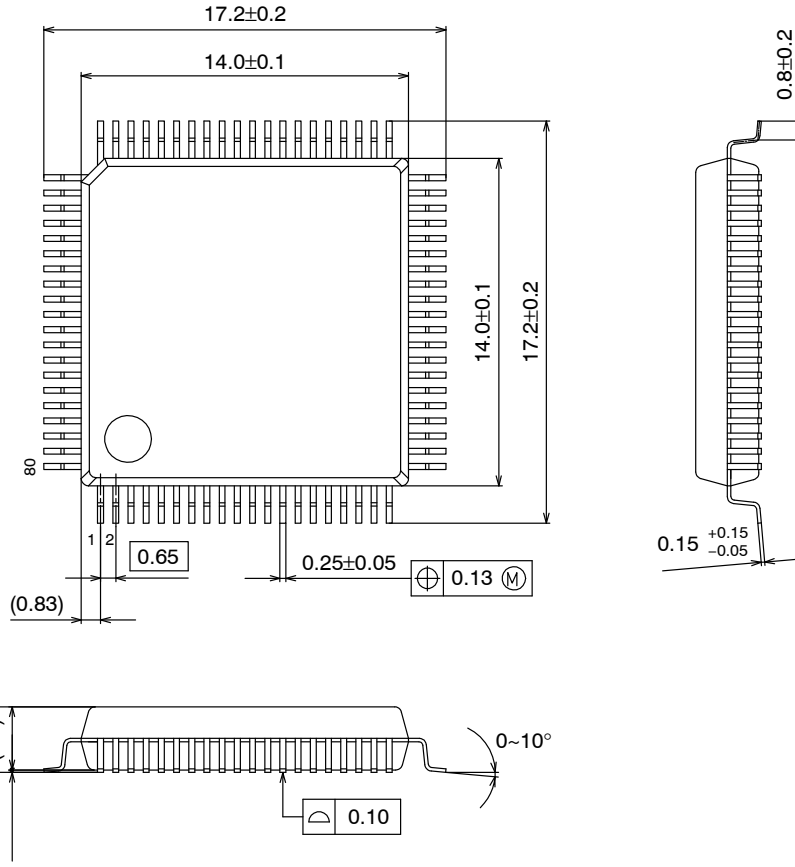


**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

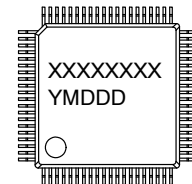


**PQFP80 14x14 / QFP80**  
**CASE 122BJ**  
**ISSUE A**

DATE 07 NOV 2013



**GENERIC MARKING DIAGRAM\***

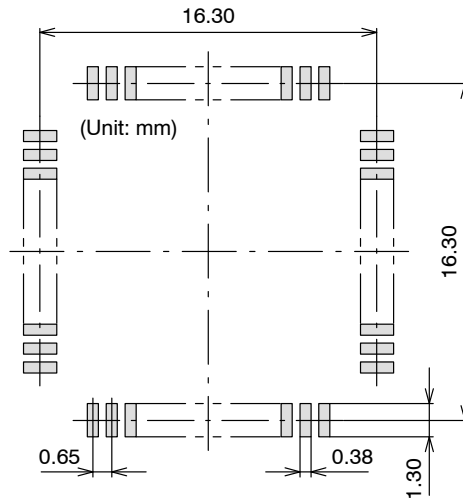


XXXXX = Specific Device Code  
 Y = Year  
 M = Month  
 DDD = Additional Traceability Data

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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<b>DESCRIPTION:</b>	<b>PQFP80 / QFP80 14X14</b>	<b>PAGE 1 OF 3</b>

**SOLDERING FOOTPRINT\***



NOTE: The measurements are not to guarantee but for reference only.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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